



SolderClean

Effective cleaning for copper, Pb solder and no-Pb solder surfaces

FEATURES

Removes oxide build up before soldering to ensure the perfect finish. Allows easy soldering on copper surfaces without tin or solder plating.

Removes oxide formed after solder reflow process

No residue left after cleaning

Non-toxic

Completely environmentally safe – can be disposed off in household drainage systems

APPLICATIONS

Apply to copper, tin or solder-plated surfaces before manual or wave soldering operations to obtain pristine surfaces ready to accept solder. Smaller boards can be wipe cleaned whereas larger boards can be briefly rinsed.

Apply to boards after hot air or convective oven-based reflow processes to remove oxide formed during the soldering process.

AVAILABILITY

Available in 100 ml spray bottles for easy application and in 250 ml refill bottles.